

IC Package Catalog

OVERVIEW

Analog Microelectronics GmbH offers its integrated circuits in SO-,SSOP- and QFN-packages. On request ICs in DIL-packages are available as well. Furthermore we offer our ICs soldered to an SOP- or SSOP-to-DIL PCB-adapter.

It is also possible to purchase our ICs as sawn wafer on blue foil or unsawn wafer (dimensions and padout on request). Please consider that a clean room is needed for the handling of wafers.

Our standard packages' dimensions and pinout can be found on the following pages:

SO-package (SOP08 and SOP16(n))	page 2
SSOP-package (SSOP16 and SSOP20)	page 3
QFN-package (QFN4x4)	page 4
QFN-package (QFN3.5x5.5)	page 5
SOP- or SSOP-to-DIL Adapter	page 6

Package Catalog

SO-PACKAGE (SMALL OUTLINE PACKAGE)

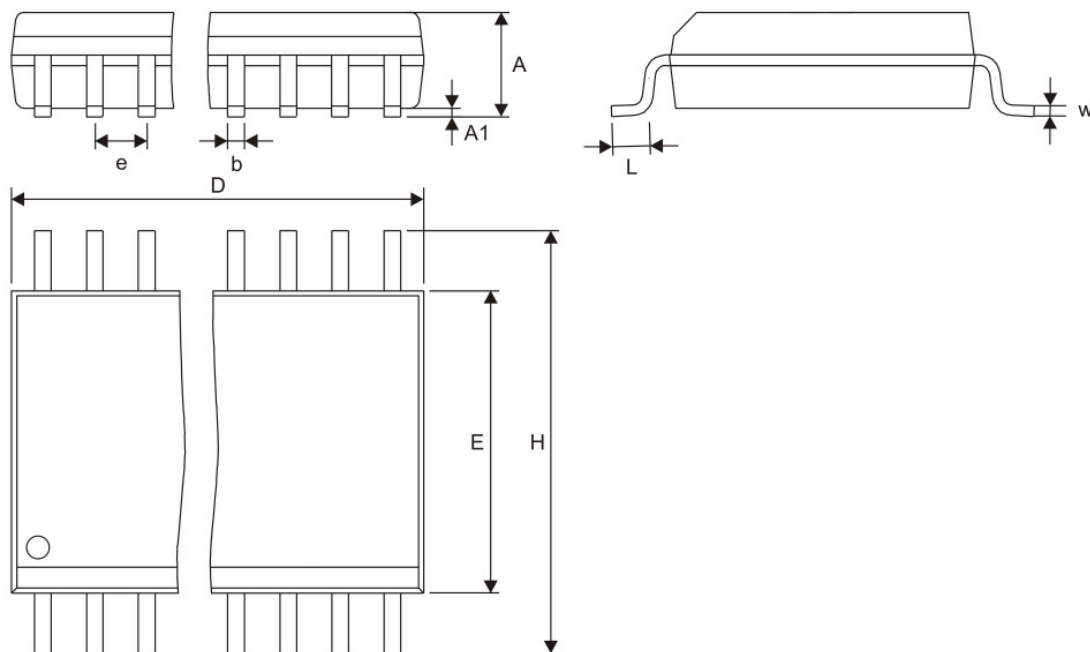


Figure 1: SO-package

Package		D	E	H	A	A1	e	b	L	w	R _{TH}
Type											
SOP08	typ.m	4.90	3.90	6.00	1.75	0.15	1.27	0.41	0.72	4°	140° K/W
SOP16 (n)	typ.	9.90	3.90	6.00	1.75	0.15	1.27	0.41	0.72	4°	115° K/W

Table 1: SO package dimensions (mm)



Figure 2: Pinout SO16 (Top View)

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SSOP-PACKAGE (SHRINK SMALL OUTLINE PACKAGE)

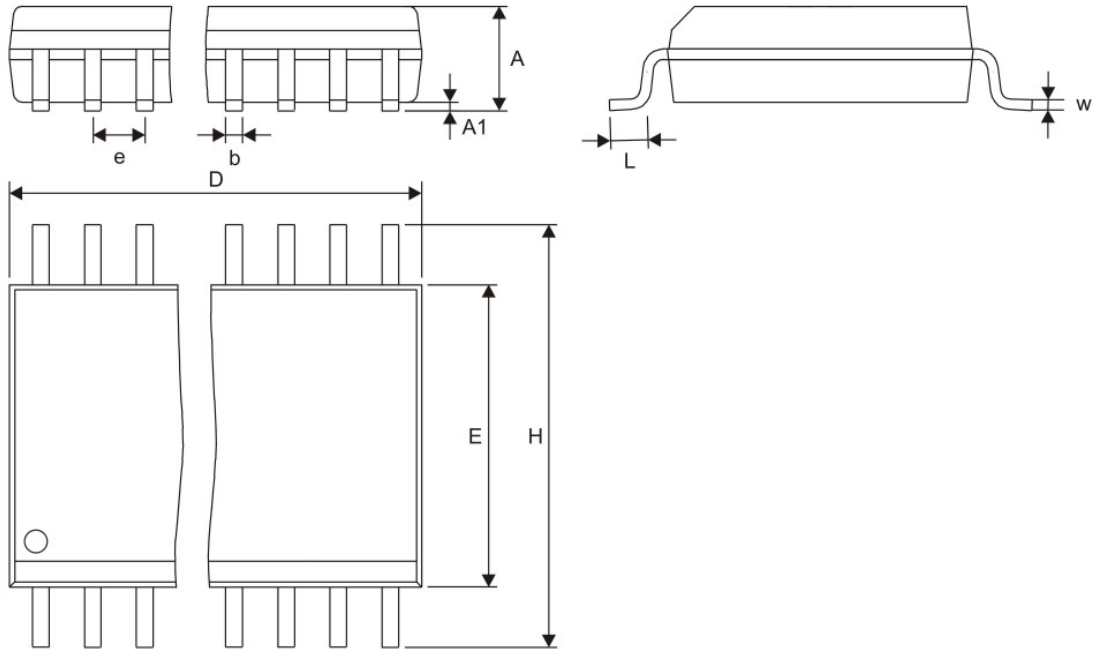


Figure 3: SSOP-package

Package		D	E	H	A	A1	e	b	L	w	R _{TH}
Type											
SSOP 16	typ.	4.90	3.90	6.00	1.75	0.15	0.635	0.26	0.72	4°	140° K/W
SSOP 20	typ.	8.65	3.90	6.00	1.75	0.15	0.635	0.26	0.72	4°	130° K/W

Table 2: SSOP package dimensions (mm)

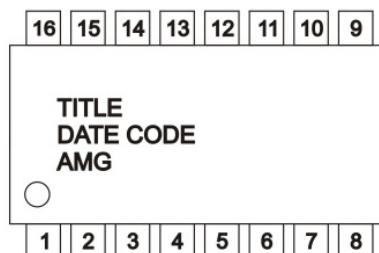


Figure 4: Pinout SSOP16 (Top View)

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QFN-PACKAGE (QFN4x4)

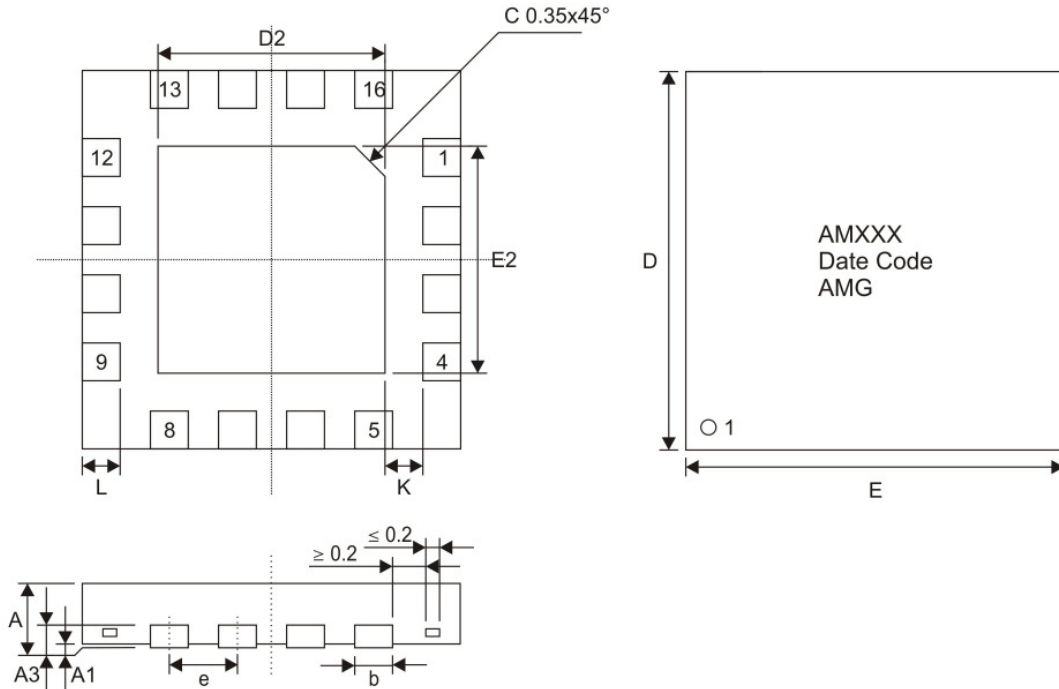


Figure 5: QFN-package (QFN4x4)

JEDEC Symbols	MO-220		
	min.	nom.	max
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.20		
b	0.25	0.30	0.35
D	4.00		
E	4.00		
e	0.65		
K	0.20		

Pad size	E2			D2			L			JEDEC CODE
	min.	nom.	max.	min.	nom.	max.	min.	nom.	max.	
102x102MIL	2.00	2.10	2.15	2.00	2.10	2.15	0.50	0.55	0.60	W(V)GGC

Table 3: QFN4x4 package dimensions (mm)

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QFN-PACKAGE (3.5x5.5)

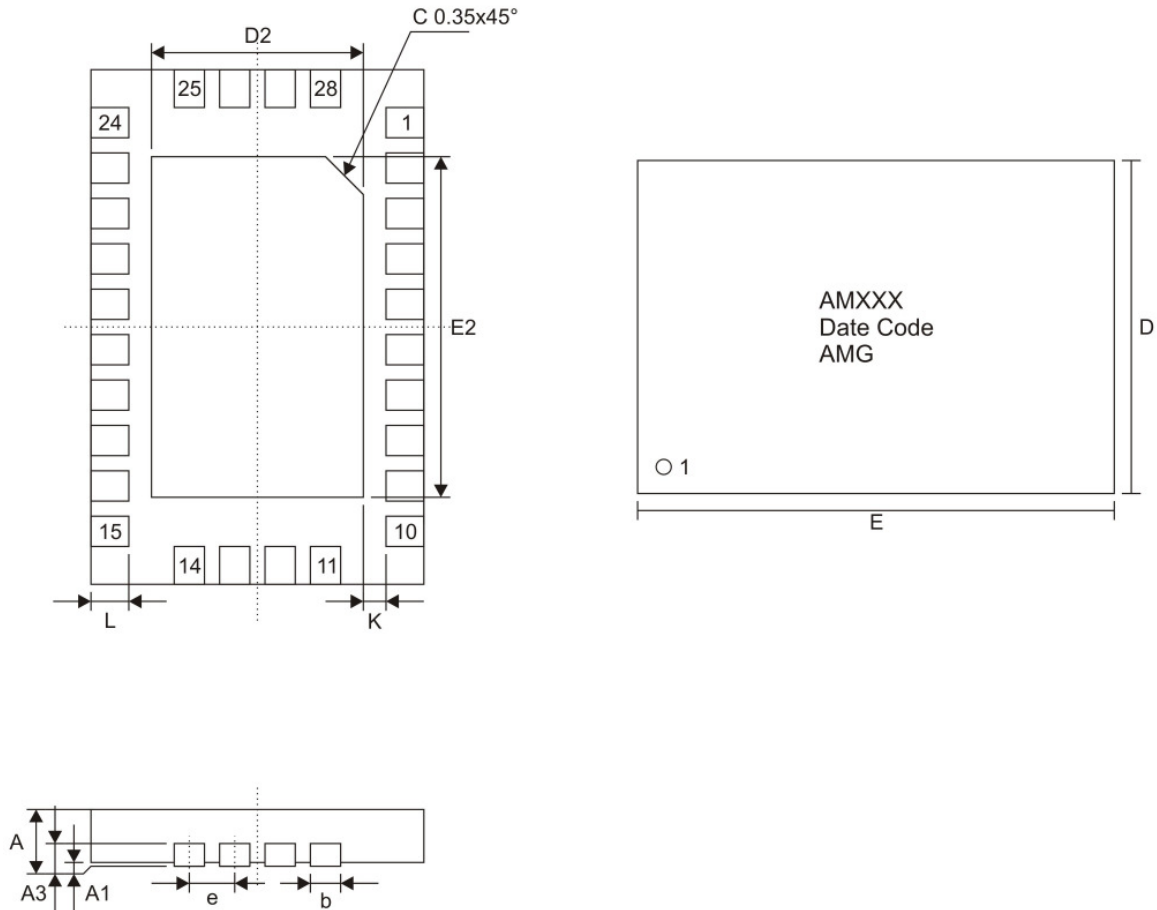


Figure 6: QFN-package (3.5x5.5)

Symbols	min.	nom.	max
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3		0.20	
b	0.20	0.25	0.30
D		3.50	
E		5.50	
e		0.5	
K	0.20		

Pad size	E2			D2			L		
	min.	nom.	max.	min.	nom.	max.	min.	nom.	max.
91x169MIL	3.950	4.05	4.10	1.95	2.05	2.10	0.35	0.40	0.45

Table 4: QFN3.5x5.5 package dimensions (mm)

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ADAPTER (SO- AND SSOP-TO-DIL-SOCKET)

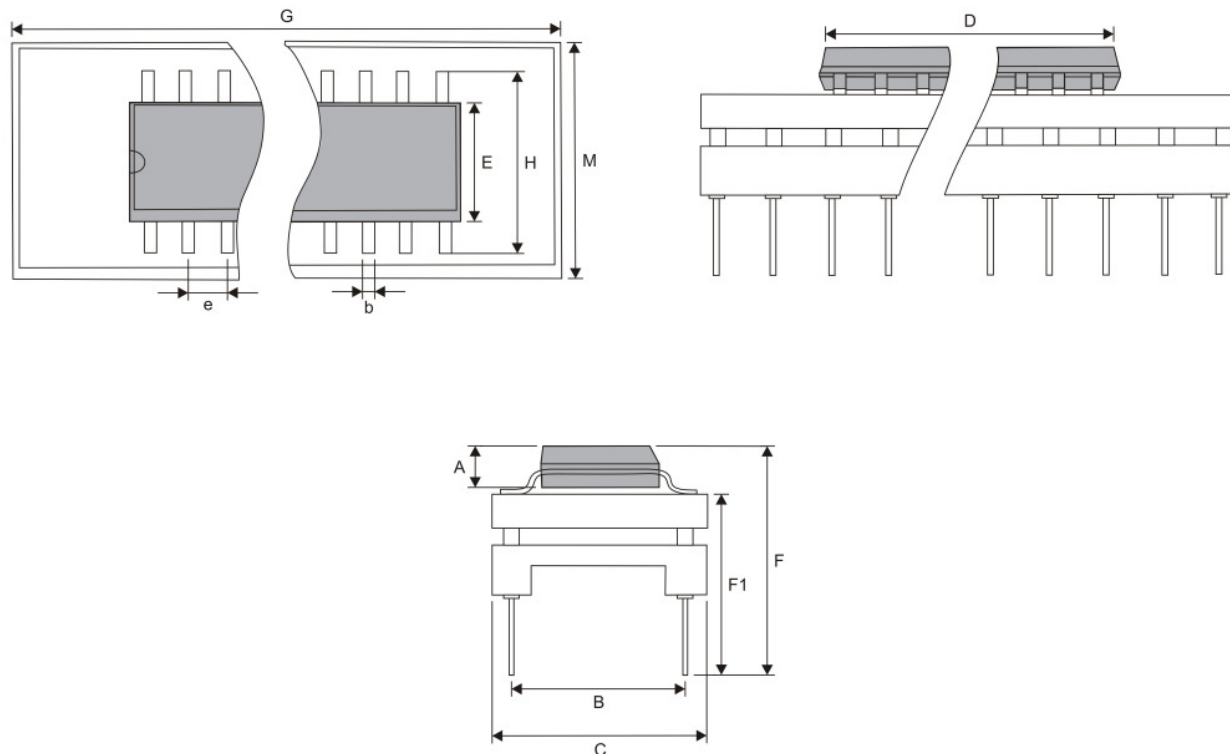


Figure 7: SO- and SSOP-to DIL-Adapter

SOP 8 to DIL8, SOP 16(n) to DIL16, SSOP 16 to DIL16, SSOP 20 to DIL20												
Package	A	B	C	D	H	F	F1	G	M	e	b	R _{TH}
Type												
SOP 8	1.7	7.62	10.0	4.90	6.00	12.70	10.30	10.00	10.00	1.27	0.41	140° K/W
SOP 16(n)	1.7	7.62	10.0	9.90	6.00	12.70	10.30	20.03	10.00	1.27	0.41	115° K/W
SSOP 16	1.7	7.62	10.0	4.90	6.00	12.70	10.30	20.03	10.00	0.635	0.26	140° K/W
SSOP 20	1.7	7.62	10.0	8.65	6.00	12.70	10.30	25.04	13.40	0.635	0.26	130° K/W

Table 5: All adapter dimensions (mm)

Analog Microelectronics GmbH reserves the right to amend any dimensions, technical data or other information contained herein without prior notification.